



## DOCUMENT CHANGE REQUEST

DCR number 147

Changes required for: N/A

Originator: MOUTON Alain

Date: 2005/03/28

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Organisation:

Status: IMPLEMENTED

Title: Generic Specification for Discrete Semiconductor Components

Number: 5000

Issue: 1

Other documents affected:

Page:

Page 26 Chart F3 Screening Tests

Paragraph:

Page 26 Chart F3 Screening Tests

Original wording:

Proposed wording:

Chart F3. Add inspection step "Hot solder Dip (if applicable)" with new "note 5" after Para 8.9.2 High and Low Temperature Electrical Measurements and before Room Temperature electrical Measurements.

Notes are renumbered to match the sequence in which they appear in chart F3

Note 5 shall read:

5. For components with hot solder dip final lead finish the hot solder dip processing shall be performed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requirements for hot solder dip are specified in ESCC basic Specification No. 23500.


Justification:

These tests are proposed to be added to prevent any risk of loss of hermeticity following the hot solder dip operation.

Such concerns were already met on Semicoa products (ESA alert EA-2003-EEE-07-A and GIDEP advisory IB7-P-03-01) and possibly met on other SMD parts from other manufacturers.

Please note that such a concern is currently under consideration by DSCC in the frame of draft N of MIL-PRF-19500.

DCR updated by the Secretariat to match mark-up of 5000 dated 3rd June 2005 and PSWG 18.

Attachments:
N/A
Modifications:
N/A
Approval signature:

Date signed:
2005-03-28